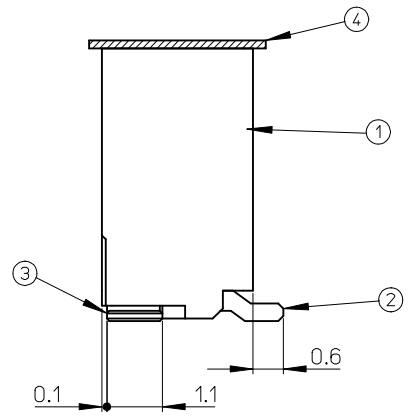
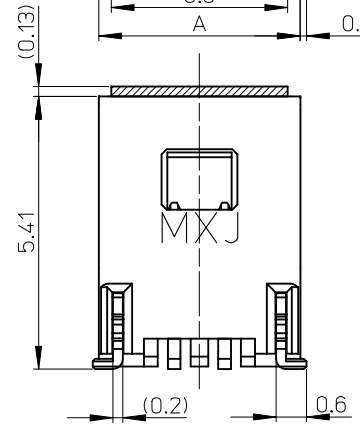


参考パターンレイアウト
 RECOMMENDED PATTERN DIM. (REF)
 SCALE:5-1 (メタルマスク厚:0.12mm)



番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	ポリアミド UL94V-0 色:自然色 POLYAMIDE, UL94V-0, COLOR:NATURAL
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 部分金メッキ:0.1μmMIN. SEPARATED GOLD PLATING ニッケルメッキ(下地):1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	りん青銅 PHOSPHOR BRONZE 錫メッキ:1.0μmMIN. TIN ニッケルメッキ(下地):1.0μmMIN. NICKEL(UNDER PLATING)
④	カバーテープ COVER TAPE	ポリイミドテープ POLYIMIDE TAPE

NOTES.

1. 嵌合相手: 501330-****
MATE WITH: 501330-****
2. ソルダーピン及びネイル平坦度は、0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- △ 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
4. 6~15極については、SD-504449-002を参照下さい。
REFER TO SD-504449-002 ABOUT 6-15CKT.
5. ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.

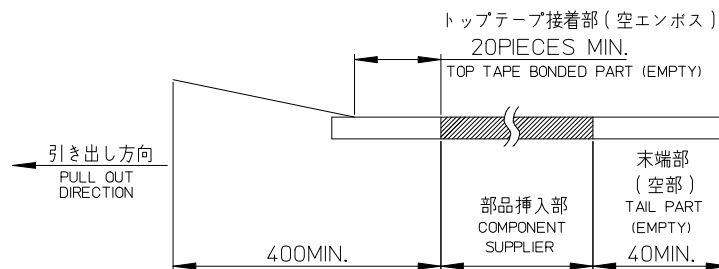
4.0	7.0	504449-0507	5
3.0	6.0	504449-0407	4
2.0	5.0	504449-0307	3
1.0	4.0	504449-0207	2
B	A	EMBOSSED PACKAGE	CKT.
		オーダー番号 ORDER NO.	

※対応可能な極数は、別途お問い合わせ下さい。

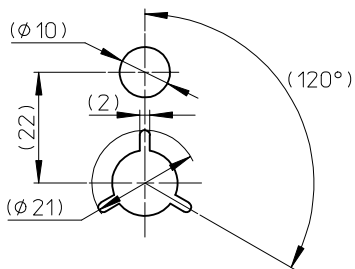
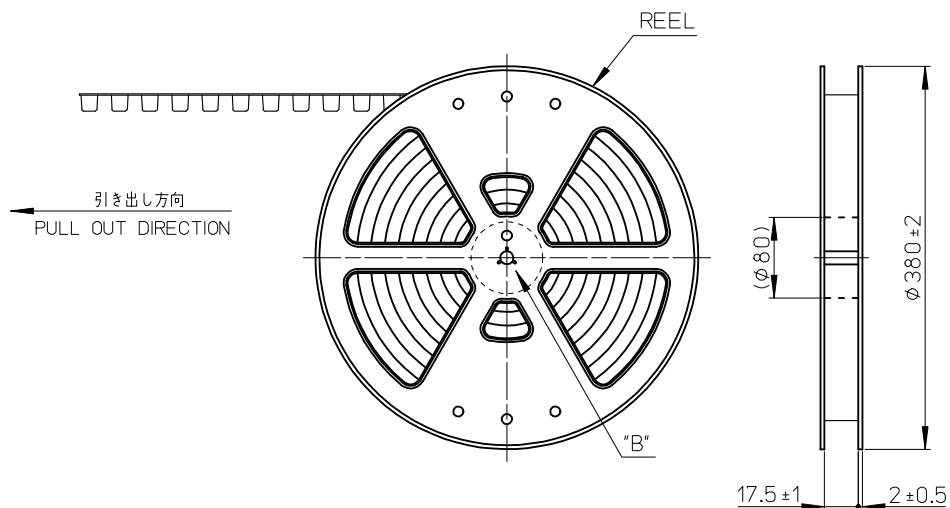
RELEASED EC NO.: J2012-1436 DRWN: KWASHIO 2012/12/13 CHKD: KASAKAWA 2012/12/14 APPR: YOITO 2012/12/21	DESCRIPTION REV O	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		CONNECTOR SERIES NO. 504449-**09			
		10 UNDER ±0.2		DRAWN BY KWASHIO DATE 2012/12/13		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 OVER 30 UNDER ±0.25		CHECKED BY DATE		TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) 2-5CKT			
		30 OVER ±0.3		APPROVED BY YOITO DATE 2012/12/21					
		ANGULAR ±3 °		MATERIAL NO. SEE TABLE					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

NOTES

1. 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
2. 梱包数量：1100個/リール
NUMBER OF CONNECTORS : 1100PIECES/REEL
3. リードテープ長さ
LEAD TAPE LENGTH

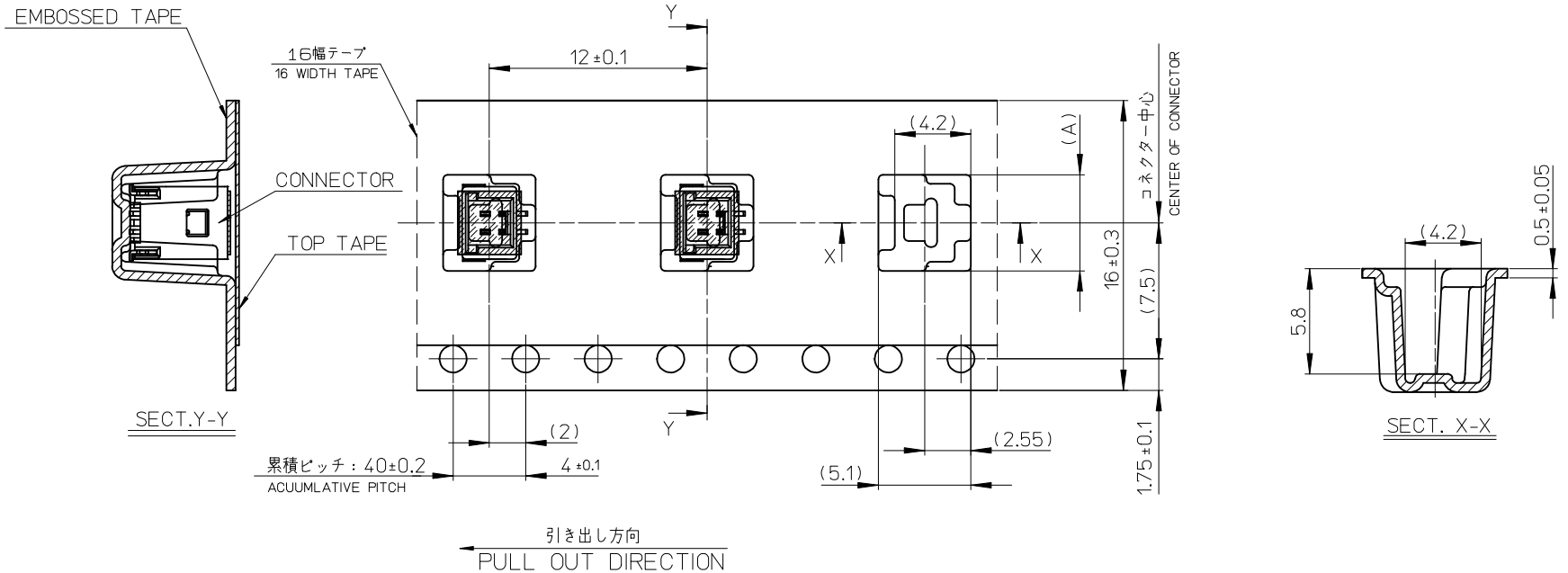


4. 材料
MATERIAL
キャリアテープ：ポリプロピレン
CARRIER TAPE : POLYPROPYLENE
トップテープ：PET、PE、REF
TOP TAPE
リール：ポリスチレン<リサイクル材を含む>
REEL : POLYSTYRENE <RECYCLE MATERIAL CONTAINED >
5. ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.
6. 本製品は乾燥剤入り、ハイバリア梱包仕様である。
(504449-0607~1507以外)
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.
(BESIDES 504449-0607~1507)



DETAIL "B"

RELEASED EC NO: J2012-1436 DRWN: KWASHIO 2012/12/13 CHKD: KASAKAWA 2012/12/14 APPR: YOITO 2012/12/21	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER ± 0.2	DRAWN BY KWASHIO	DATE 2012/12/13	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG		
		10 OVER 30 UNDER ± 0.25	CHECKED BY	DATE			
		30 OVER ± 0.3	APPROVED BY YOITO	DATE 2012/12/21	molex DOCUMENT NO. SD-504449-003 SHEET NO. 1 OF 2		
		ANGULAR $\pm 1^\circ$ DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 2				
REV 0	SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



8.3	504449-0507	5
7.3	504449-0407	4
6.3	504449-0307	3
5.3	504449-0207	2
(A)	EMBOSSED PACKAGE	CKT.
	オーダー番号 ORDER NO.	

CONNECTOR SERIES NO. 504449-***9

SEE SHEET1 EC NO. J2012-1436 DRWN:KWASHIO 2012/12/13 CHKD:KASAKAWA 2012/12/14 APPR:YOITO 2012/12/21 REV: 0	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED) 10 UNDER ± 0.2 10 OVER 30 UNDER ± 0.25 30 OVER ± 0.3 ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		DRAWN BY KWASHIO	DATE 2012/12/13	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG			
		CHECKED BY	DATE	molex			
		APPROVED BY YOITO	DATE 2012/12/21	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-504449-003	SHEET NO. 2 OF 2	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					